

# Power MOSFET

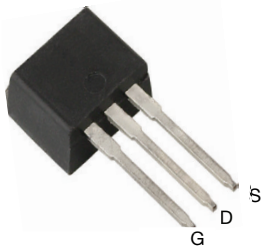
PRODUCT SUMMARY		
$V_{DS}$ (V)	950	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$	5.4
$Q_g$ (Max.) (nC)	78	
$Q_{gs}$ (nC)	10	
$Q_{gd}$ (nC)	42	
Configuration	Single	

## FEATURES

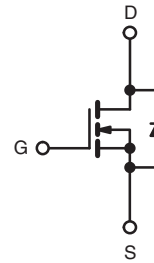
- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



TO-262



Top View




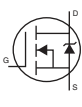
N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)				
PARAMETER	SYMBOL	LIMITE	UNIT	
Drain-Source Voltage	$V_{DS}$	950	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$		
Continuous Drain Current	$V_{GS}$ at 10 V	$T_C = 25\text{ }^\circ\text{C}$	A	
		$T_C = 100\text{ }^\circ\text{C}$		
Pulsed Drain Current <sup>a</sup>	$I_{DM}$	14		
Linear Derating Factor		1.0	W/ $^\circ\text{C}$	
Single Pulse Avalanche Energy <sup>b</sup>	$E_{AS}$	250	mJ	
Repetitive Avalanche Current <sup>a</sup>	$I_{AR}$	3.6	A	
Repetitive Avalanche Energy <sup>a</sup>	$E_{AR}$	13	mJ	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	125	W
Peak Diode Recovery $dV/dt$ <sup>c</sup>		$dV/dt$	1.5	V/ns
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>	
Mounting Torque	6-32 or M3 screw		10	lbf · in
			1.1	N · m

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 36\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 3.6\text{ A}$  (see fig. 12).
- $I_{SD} \leq 3.6\text{ A}$ ,  $dI/dt \leq 70\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq 600$ ,  $T_J \leq 150\text{ }^\circ\text{C}$ .
- 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	62	°C/W
Case-to-Sink, Flat, Greased Surface	$R_{thCS}$	0.50	-	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.0	

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		950	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$		-	1.1	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 900\text{ V}, V_{GS} = 0\text{ V}$		-	-	100	$\mu\text{A}$
		$V_{DS} = 720\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	500	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 2.2\text{ A}^b$	-	5.4	-	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = 100\text{ V}, I_D = 2.2\text{ A}^b$		2.3	-	-	S
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz},$ see fig. 5		-	1200	-	pF
Output Capacitance	$C_{oss}$			-	320	-	
Reverse Transfer Capacitance	$C_{rss}$			-	200	-	
Total Gate Charge	$Q_g$	$V_{GS} = 10\text{ V}$	$I_D = 3.6\text{ A}, V_{DS} = 360\text{ V},$ see fig. 6 and 13 <sup>b</sup>	-	-	78	nC
Gate-Source Charge	$Q_{gs}$			-	-	10	
Gate-Drain Charge	$Q_{gd}$			-	-	42	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 450\text{ V}, I_D = 3.6\text{ A},$ $R_g = 12\text{ }\Omega, R_D = 120\text{ }\Omega,$ see fig. 10 <sup>b</sup>		-	14	-	ns
Rise Time	$t_r$			-	25	-	
Turn-Off Delay Time	$t_{d(off)}$			-	90	-	
Fall Time	$t_f$			-	30	-	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	nH
Internal Source Inductance	$L_S$			-	7.5	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	3.6	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	14	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 3.6\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.8	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 3.6\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	430	650	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			-	1.4	2.1	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

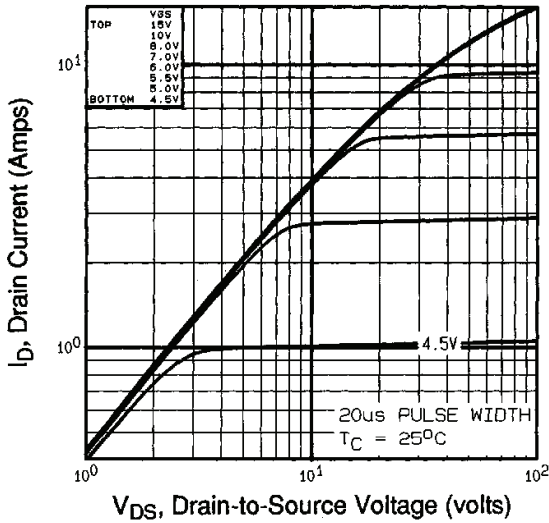


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$

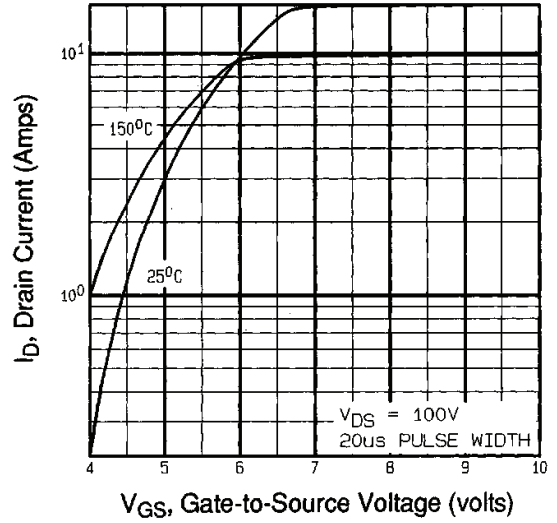


Fig. 3 - Typical Transfer Characteristics

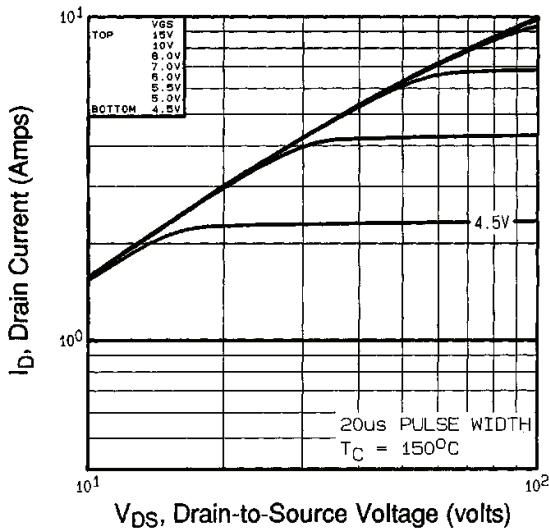


Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$

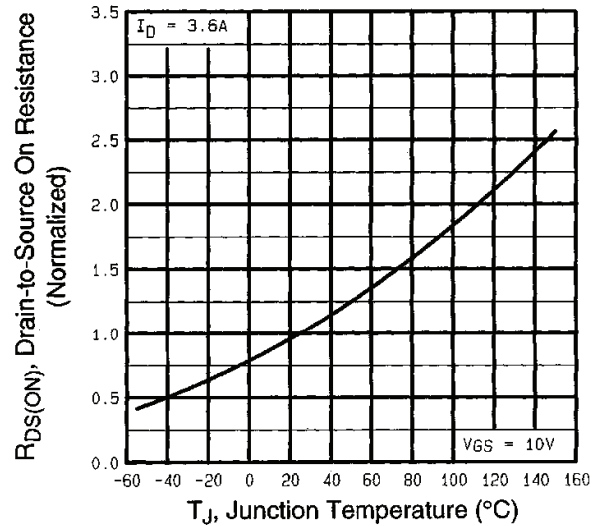


Fig. 4 - Normalized On-Resistance vs. Temperature

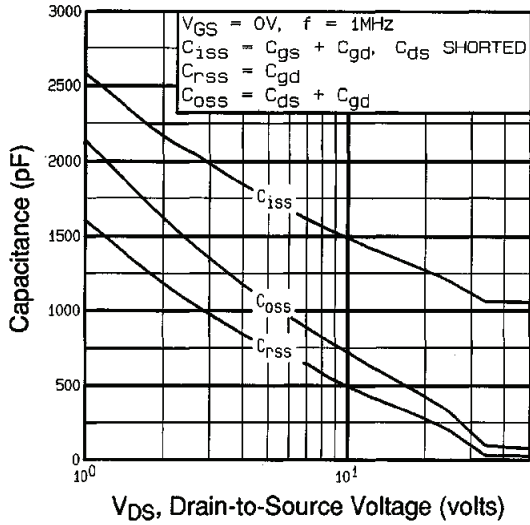


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

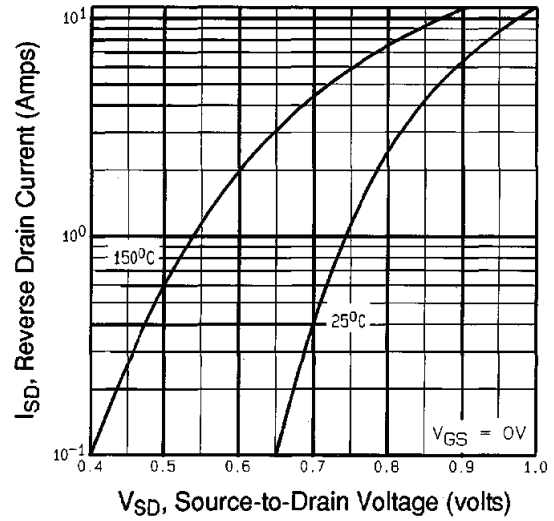


Fig. 7 - Typical Source-Drain Diode Forward Voltage

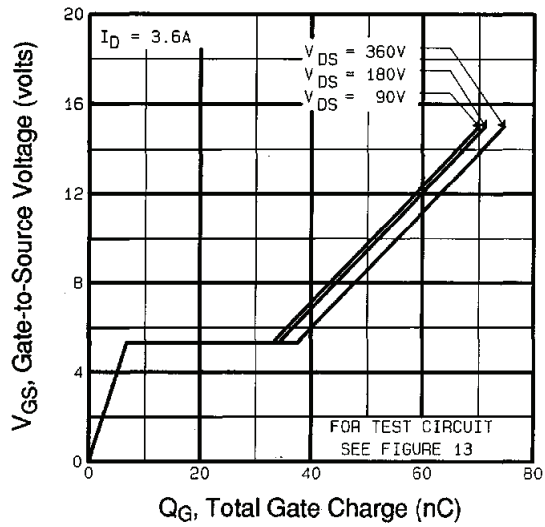


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

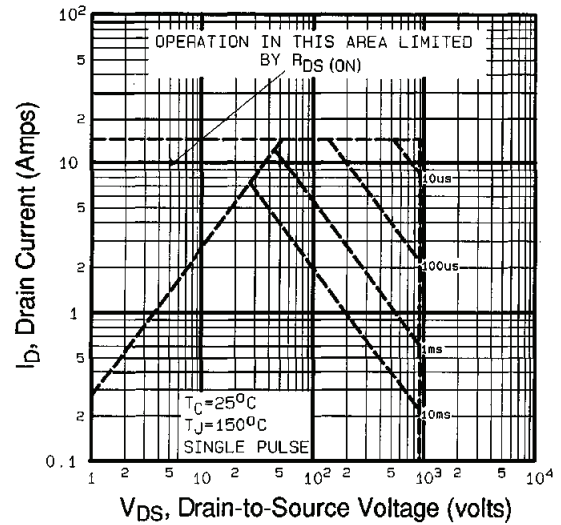


Fig. 8 - Maximum Safe Operating Area

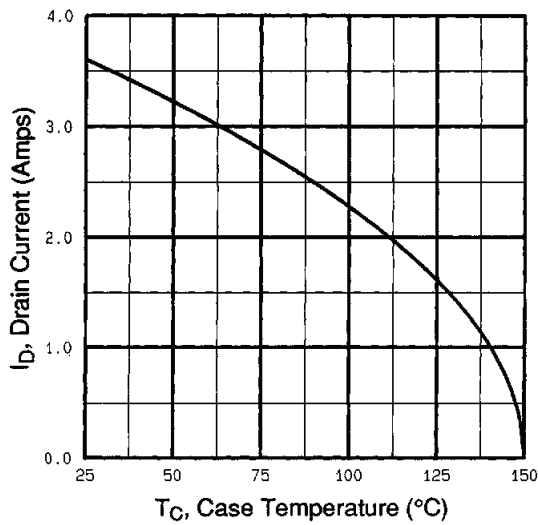


Fig. 9 - Maximum Drain Current vs. Case Temperature

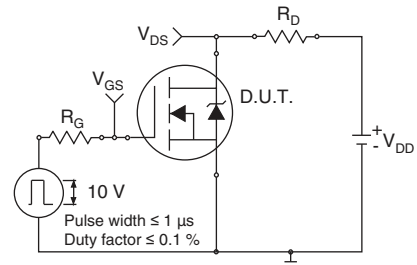


Fig. 10a - Switching Time Test Circuit

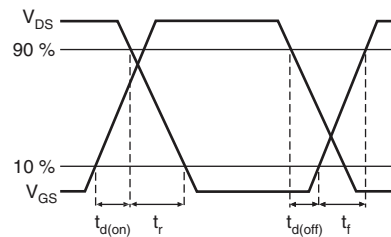


Fig. 10b - Switching Time Waveforms

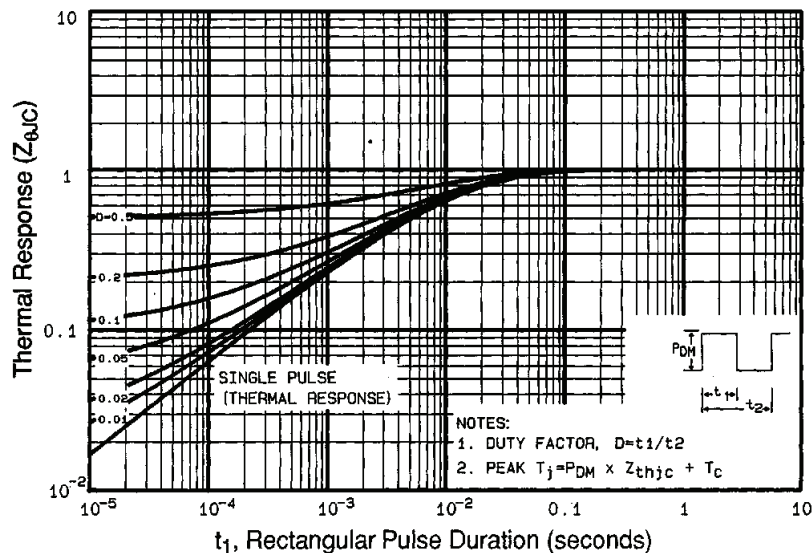


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

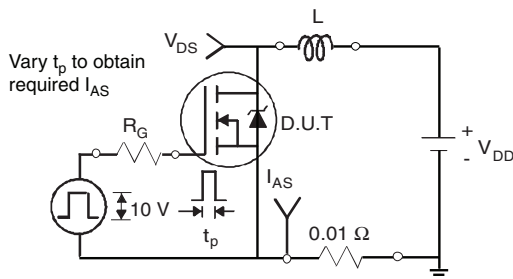


Fig. 12a - Unclamped Inductive Test Circuit

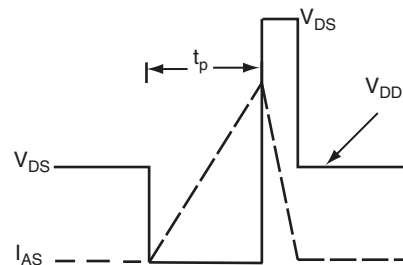


Fig. 12b - Unclamped Inductive Waveforms

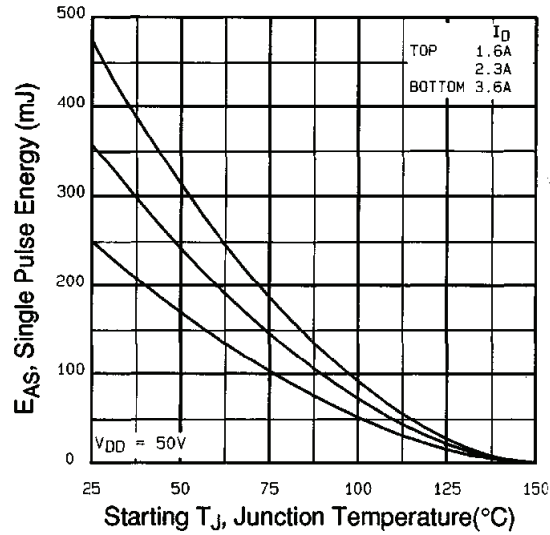


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

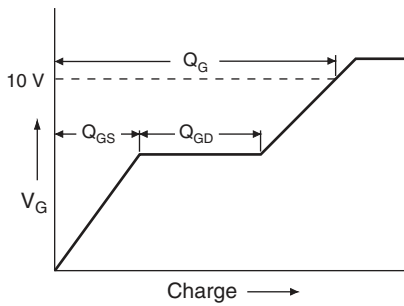


Fig. 13a - Basic Gate Charge Waveform

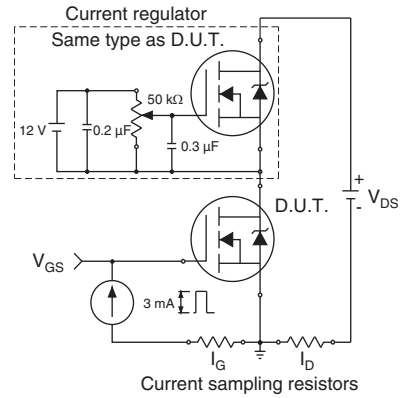
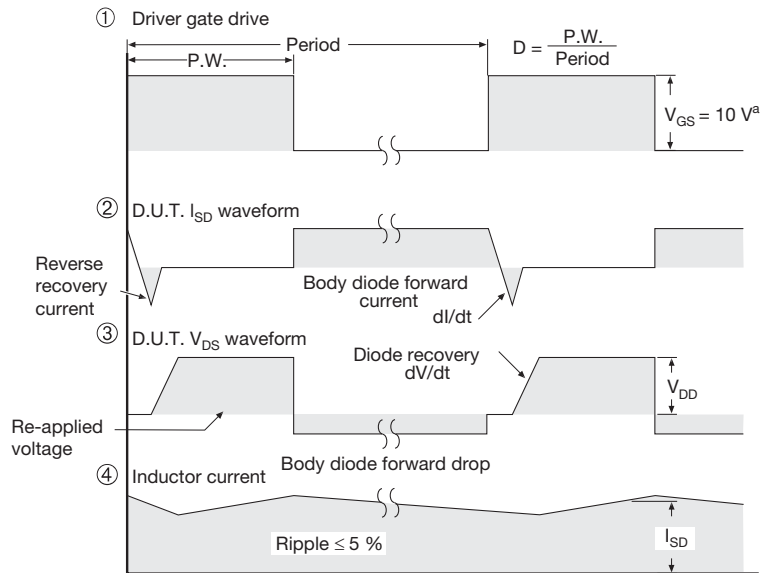
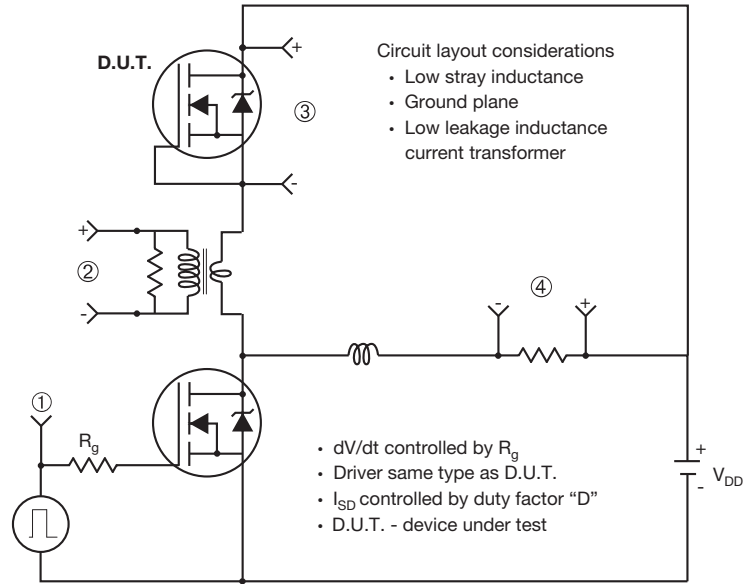


Fig. 13b - Gate Charge Test Circuit

**Peak Diode Recovery dV/dt Test Circuit**

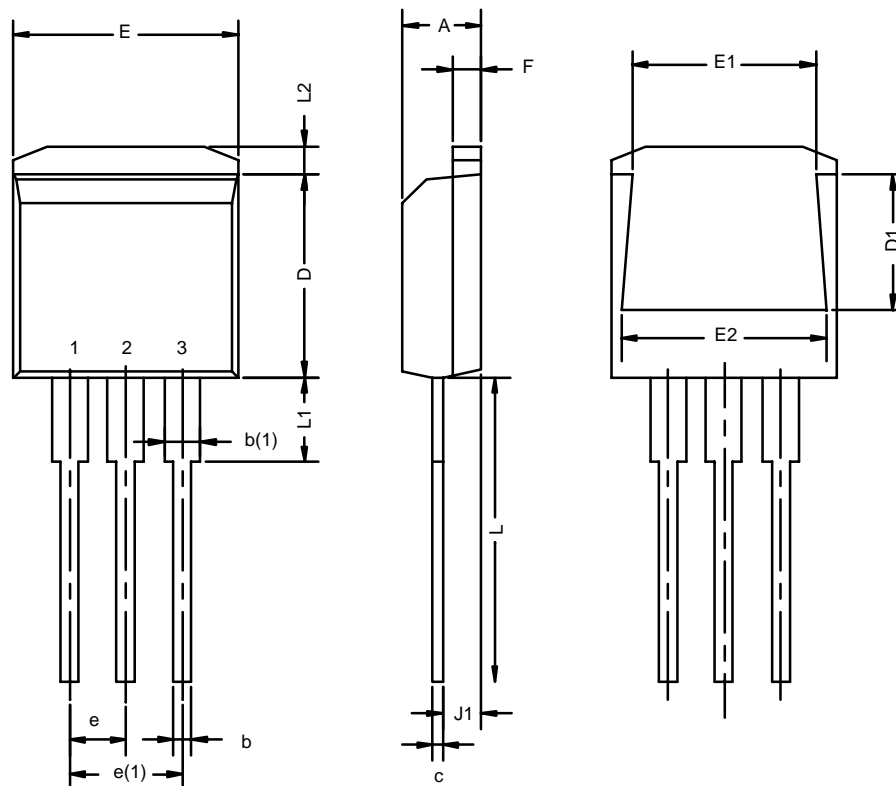


**Note**

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

**TO-262: 3-LEAD**



Dim	MILLIMETERS*		INCHES	
	Min	Max	Min	Max
<b>A</b>	4.32	4.70	0.170	0.185
<b>b</b>	0.64	1.00	0.025	0.039
<b>b(1)</b>	1.14	1.40	0.045	0.055
<b>c</b>	0.36	0.50	0.014	0.020
<b>D</b>	8.64	9.65	0.340	0.380
<b>D1</b>	5.59	6.10	0.220	0.240
<b>e</b>	2.41	2.67	0.095	0.105
<b>e(1)</b>	4.95	5.33	0.195	0.210
<b>E</b>	10.03	10.41	0.395	0.410
<b>E1</b>	7.87	8.64	0.310	0.340
<b>E2</b>	9.02	9.53	0.355	0.375
<b>F</b>	1.14	1.40	0.045	0.055
<b>J1</b>	2.41	2.79	0.095	0.110
<b>L</b>	13.08	14.22	0.515	0.560
<b>L1</b>	-	3.81	-	0.150
<b>L2</b>	1.02	1.40	0.040	0.055

ECN: T-02234—Rev. C, 14-Oct-02  
DWG: 5855

\*Use millimeters as the primary measurement



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